

## HIGH-POWER NPN SILICON TRANSISTORS

... designed for use in industrial power amplifiers and switching circuit applications.

### FEATURES:

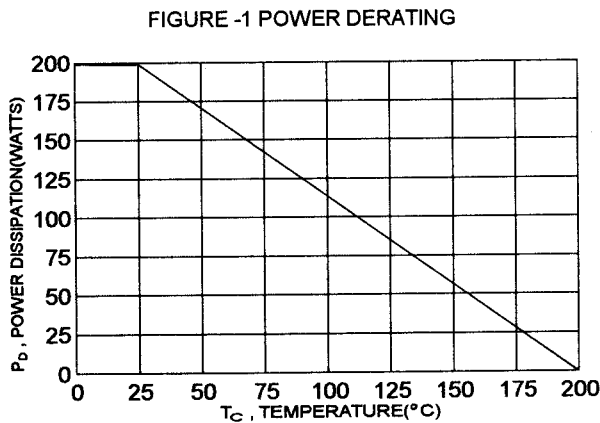
- \* High DC Current Gain  
 $h_{FE}=30-120 @ I_C=10A$   
 $=12 \text{ (Min)} @ I_C=25A$
- \* Low Collector-Emitter Saturation Voltage  
 $V_{CE(SAT)} = 1.0V \text{ (Max.)} @ I_C = 10 A, I_B = 1.0A$
- \* Complement to 2N6436-38

### MAXIMUM RATINGS

Characteristic	Symbol	2N6338	2N6339	2N6340	2N6341	Unit
Collector-Emitter Voltage	$V_{CEO}$	100	120	140	150	V
Collector-Base Voltage	$V_{CBO}$	120	140	160	180	V
Emitter-Base Voltage	$V_{EBO}$	6.0				V
Collector Current-Continuous -Peak	$I_C$	25 50				A
Base Current	$I_B$	10				A
Total Power Dissipation @ $T_C=25^\circ C$ Derate above $25^\circ C$	$P_D$	200 1.14				W W/ $^\circ C$
Operating and Storage Junction Temperature Range	$T_J, T_{STG}$	-65 to +200				$^\circ C$

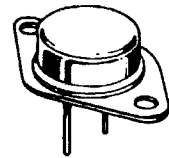
### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance Junction to Case	$R_{\theta jc}$	0.875	$^\circ C/W$

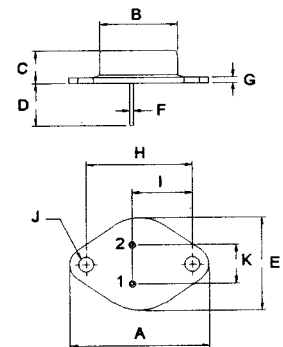


**NPN**  
**2N6338**  
**2N6339**  
**2N6340**  
**2N6341**

25 AMPERE  
 POWER TRANSISTOR  
 NPN SILICON  
 100-150 VOLTS  
 200 WATTS



TO-3



PIN 1. BASE  
 2. EMITTER  
 COLLECTOR (CASE)

DIM	MILLIMETERS	
	MIN	MAX
A	38.75	39.96
B	19.28	22.23
C	7.96	9.28
D	11.18	12.19
E	25.20	26.67
F	0.92	1.09
G	1.38	1.62
H	29.90	30.40
I	16.64	17.30
J	3.88	4.36
K	10.67	11.18

**ELECTRICAL CHARACTERISTICS (  $T_c = 25^\circ\text{C}$  unless otherwise noted )**

Characteristic	Symbol	Min	Max	Unit
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**OFF CHARACTERISTICS**

Collector -Emitter Sustaining Voltage (1) ( $I_c = 50\text{mA}$ , $I_B = 0$ )	2N6338 2N6339 2N6340 2N6341	$V_{CE(sus)}$	100 120 140 150	V
Collector Cutoff Current ( $V_{CE} = 50\text{V}$ , $I_B = 0$ ) ( $V_{CE} = 60\text{V}$ , $I_B = 0$ ) ( $V_{CE} = 70\text{V}$ , $I_B = 0$ ) ( $V_{CE} = 75\text{V}$ , $I_B = 0$ )	2N6338 2N6339 2N6340 2N6341	$I_{CEO}$	50 50 50 50	$\mu\text{A}$
Collector Cutoff Current ( $V_{CB} = \text{Rated } V_{CB}$ , $I_E = 0$ )		$I_{CBO}$	10	$\mu\text{A}$
Emitter Cutoff Current ( $V_{EB} = 6.0\text{V}$ , $I_C = 0$ )		$I_{EBO}$	100	$\mu\text{A}$

**ON CHARACTERISTICS (1)**

DC Current Gain ( $I_c = 0.5\text{A}$ , $V_{CE} = 2.0\text{V}$ ) ( $I_c = 10\text{A}$ , $V_{CE} = 2.0\text{V}$ ) ( $I_c = 25\text{A}$ , $V_{CE} = 2.0\text{V}$ )		$h_{FE}$	50 30 12	120	
Collector-Emitter Saturation Voltage ( $I_c = 10\text{A}$ , $I_B = 1.0\text{A}$ ) ( $I_c = 25\text{A}$ , $I_B = 2.5\text{A}$ )		$V_{CE(sat)}$	1.0 1.8		V
Base-Emitter Saturation Voltage ( $I_c = 10\text{A}$ , $I_B = 1.0\text{A}$ ) ( $I_c = 25\text{A}$ , $I_B = 2.5\text{A}$ )		$V_{BE(sat)}$	1.8 2.5		V
Base-Emitter On Voltage ( $I_c = 10\text{A}$ , $V_{CE} = 2.0\text{V}$ )		$V_{BE(on)}$	1.8		V

**DYNAMIC CHARATERISTICS**

Current-Gain Bandwidth Product (2) ( $I_c = 1.0\text{A}$ , $V_{CE} = 10\text{V}$ , $f = 10\text{MHz}$ )		$f_T$	40		MHz
Output Capacitance ( $V_{CB} = 10\text{V}$ , $I_E = 0$ , $f = 0.1\text{MHz}$ )		$C_{ob}$	300		pF

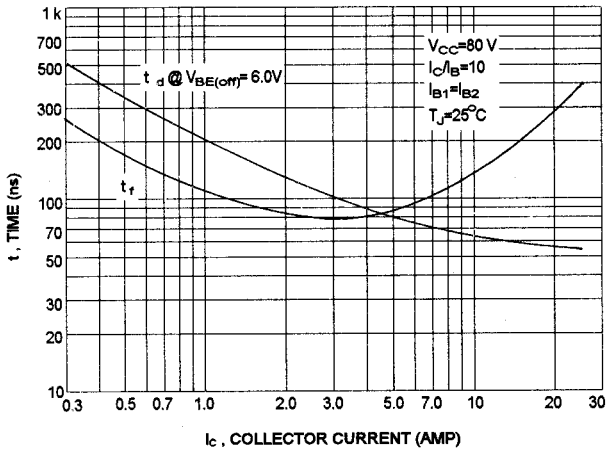
**SWTCHING CHARACTERISTICS**

Rise Time	$V_{CC} = 80\text{V}$ , $I_c = 10\text{A}$ $I_{B1} = -I_{B2} = 1\text{A}$ , $V_{BE(off)} = 6\text{V}$	$t_r$	0.4	$\mu\text{s}$
Storage Time		$t_s$	1.5	$\mu\text{s}$
Fall Time		$t_f$	0.6	$\mu\text{s}$

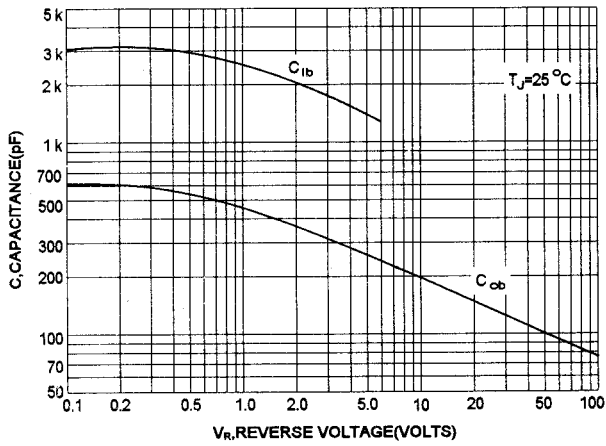
(1) Pulse Test: Pulse width =  $300\ \mu\text{s}$ , Duty Cycle  $\leq 2.0\%$

(2)  $f_T = |h_{fe}| \cdot f_{test}$

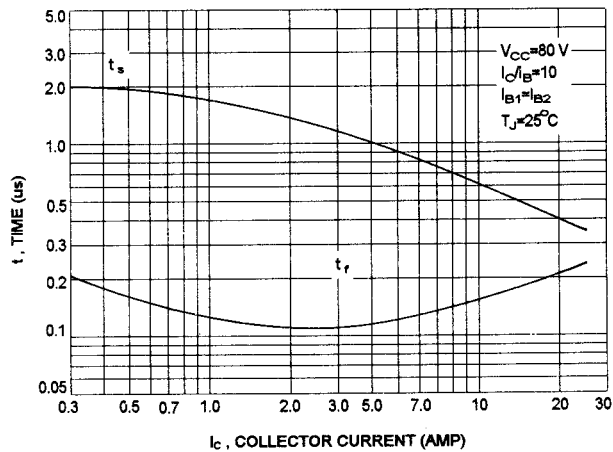
TURN-ON TIME



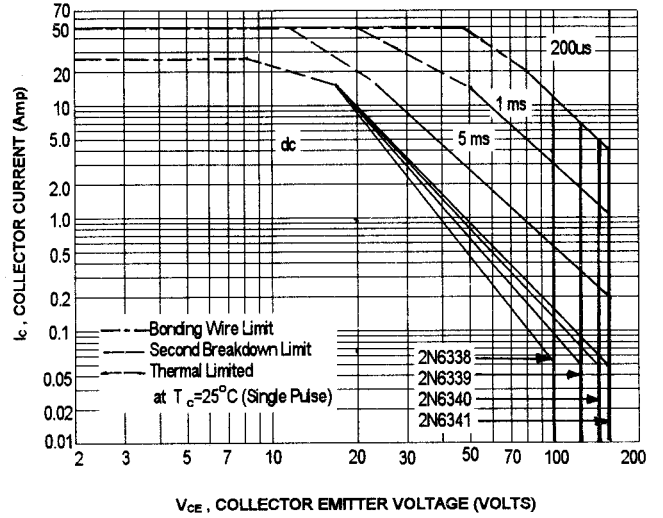
CAPACITANCES



TURN-OFF TIME



ACTIVE-REGION SAFE OPERATING AREA (SOA)



There are two limitation on the power handling ability of a transistor: average junction temperature and second breakdown safe operating area curves indicate  $I_C$ - $V_{CE}$  limits of the transistor that must be observed for reliable operation i.e., the transistor must not be subjected to greater dissipation than curves indicate.

The data of SOA curve is base on  $T_{J(PK)} = 200^\circ C$ ;  $T_c$  is variable depending on conditions. second breakdown pulse limits are valid for duty cycles to 10% provided  $T_{J(PK)} \leq 200^\circ C$ . At high case temperatures, thermal limitation will reduce the power that can be handled to values less than the limitations imposed by second breakdown.